

REMARKS

Claims 1-21 are pending in this application. Claims 18-21 have been withdrawn from consideration. By this Amendment, the title of the invention is amended; and claims 1, 3, 18 and 21 are amended. No new matter is added. In view of the foregoing amendments and following remarks, reconsideration and allowance are respectfully requested.

The courtesies extended to Applicant's representative by Examiner Williams at the interview held December 6, 2004, are appreciated. The reasons presented at the interview as warranting favorable action are incorporated into the remarks below and constitute Applicant's record of the interview.

I. The Specification Satisfies All Formal Requirements

The Office Action objects to the title of the invention. The title of the invention is amended to obviate the objection. Withdrawal of the objection is respectfully requested.

II. Rejection Under 35 U.S.C. §102(b)

The Office Action rejects claims 1-17 under 35 U.S.C. §102(b) over U.S. Patent No. 5,973,931 to Fukasawa. This rejection is respectfully traversed.

Fukasawa does not disclose "a resist layer covering at least the penetration hole, the penetration hole being formed in a region along a periphery of the land," as recited in claim 1. Fukasawa discloses that "in the first preferred embodiment described above a gap of over 0.05 mm is provided between the land 16 and the pattern-protecting film 17 "(col. 4, lines 41-48; Fig. 4b). As shown in Fig. 4b, the pattern forming film 17 does not cover the peripheral opening, but only partially covers the peripheral opening up to the diameter D1, leaving an uncovered gap surrounding the land 16. Accordingly, as acknowledged during the personal interview, Fukasawa does not anticipate a resist layer covering at least the penetration hole, as recited in claim 1.

Further, as shown in Fig. 4B of Fukasawa, even in the case when the penetration hole is exposed from the resist layer, stress is concentrated on the edge of the land 16 and the connecting pattern 16a, which is exposed from the pattern-protecting film 17, when mounting a semiconductor chip. However, the resist layer covering at least the penetration hole, as recited in claim 1, prevents this concentration of stress. Thus, claim 1 is not anticipated by Fukasawa.

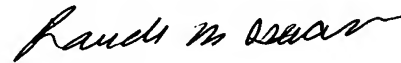
Claims 2-17 depend from claim 1, and thus, claims 2-17 are also not anticipated by Fukasawa. Accordingly, reconsideration and withdrawal of the rejection are respectfully requested.

III. Conclusion

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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